

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Markus Brunnbauer	07/20/2007
Thorsten Meyer	07/10/2007
Stephan Bradl	07/05/2007
Ralf Plieninger	07/15/2007
RECEIVING PARTY DATA	
Name:	Infineon Technologies AG
Street Address:	Am Campeon 1 - 12
City:	Neubiberg
State/Country:	GERMANY
Postal Code:	85579
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11746936
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NAME OF SUBMITTER:	Lawrence D. Eisen
Total Attachments: 2	

OP \$40.00 11746936

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PATENT
REEL: 019629 FRAME: 0693

ASSIGNMENT

For good and valuable consideration, WE, Markus Brunnbauer, a citizen of Germany, residing at Auf den Hoehe 8, 93138 Lappersdorf, Germany; Thorsten Meyer, a citizen of Germany, residing at Altdorferstrasse 3a, 93049 Regensburg, Germany; Stephan Bradl, a citizen of Germany, residing at Ellen-Ammann-Weg 1, 93051 Regensburg, Germany; and Ralf Plieninger, a citizen of Germany, residing at Boehmerwaldstr. 37, 85586 Poing, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infinion Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, 85579 Neubiberg, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on May 10, 2007 as US. Application Serial No. 11/746,936,

entitled: **Structure for Electrostatic Discharge in Embedded Wafer Level Packages**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: _____

Markus Brunnbauer

DATE: _____

20.7.07

SIGNATURE:


Thorsten Meyer

DATE:

10.07.07

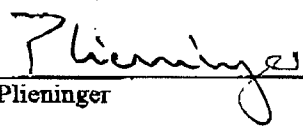
SIGNATURE:


Stephan Bradl

DATE:

05. Juli 2007

SIGNATURE:


Ralf Plieninger

DATE:

15.7.07